Qdos Choose Orbotech Paragon™-UltraLaser Direct Imaging (LDI) System for New MIS Production

Orbotech Ltd., a global technology leader in solutions for printed circuit boards (PCBs) and IC substrates, announced today that Qdos (Malaysia), a Suiwah Corp. company, has purchased Orbotech’s Paragon™-Ultra laser direct imaging (LDI) system. Orbotech's field-proven Paragon™-Ultra LDI systems deliver the highest imaging accuracy and yields to meet the increasing demands of the fast-growing QFN, FC and BGA packaging segment.

YAVNE, ISRAEL (PRWEB) July 14, 2014 -- ORBOTECH LTD. (NASDAQ/GSM SYMBOL: ORBK) Orbotech Ltd., a global technology leader in solutions for printed circuit boards (PCBs) and IC substrates, announced today that Qdos (Malaysia), a Suiwah Corp. company, has purchased Orbotech’s Paragon™-Ultra laser direct imaging (LDI) system. Orbotech's field-proven Paragon™-Ultra LDI systems deliver the highest imaging accuracy and yields to meet the increasing demands of the fast-growing QFN, FC and BGA packaging segment.

Qdos chose Orbotech’s Paragon-Ultra LDI system in order to accomplish their objectives of achieving higher yields, enhanced productivity, faster TTM and increased flexibility in production of Molded Interconnect Substrates (MIS) technology.

“To maintain our current leadership positioning, we cannot afford to compromise on accuracy or throughput. We chose Orbotech’s Paragon-Ultra LDI system for our MIS production after witnessing first-hand the system’s ability to handle complex applications with precision speed and accuracy”, says Jeffrey Hwang, Executive Director at Qdos.

MIS is a new technology serving as an improved alternative to traditional lead frame and BGA substrates. The use of build-up technology offers a breakthrough from the conventional polymer core, enabling production of super-fine circuitry for enhanced performance applications, particularly those with 4G, low noise and high frequency requirements. Orbotech’s unique LSO Technology™ for LDI ensures the highest level of imaging quality at super-fine resolutions for feature sizes down to 8μm and minimum pitch of 20μm, enabling cost-effective MIS production.

“We are proud that Qdos, a world leader in MIS innovation, has selected Orbotech as their LDI technology vendor-of-choice and appreciate the opportunity to facilitate the production of this game-changing technology”, says Arik Gordon, PCB Division President at Orbotech, Ltd.

Qdos showcased both their existing Flexible Printed Circuits (FPC) and their new MIS product lines (produced using Orbotech’s Paragon-Ultra LDI) at this year’s Semicon West convention.

About Qdos (Malaysia)

Established in 1994, Qdos is a pioneer manufacturer of Flexible Printed Circuits (FPC) in Malaysia, owned by Suiwah Corp, a main-board-listed conglomerate in Malaysia. Equipped with highly automated state-of-the-art facilities, Qdos provides a comprehensive FPC and MIS solutions, covering circuit design, prototype fabrication, mass production and SMT assembly. As a reliable partner and world-class manufacturer, Qdos is
certified with ISO9001, ISO/TS16949, ISO14001, Sony Green Partnership and Canon Green Procurement. Our commitment towards excellence in FPC engineering has earned Qdos a reputable track record and long-term partnerships with numerous blue-chip OEMs. Qdos is a proud appointed vendor to telecommunications, automotive, consumer electronics, military and aerospace customers in more than 20 countries including the United States, Germany and Japan. In 2013, we ramped up FPC production and also launched a new product family, Molded Interconnect Substrate (MIS). MIS technology redefines coreless IC substrates. This cutting-edge technology provides an innovative solution to BGA, QFN and fine pitch flip-chip semiconductor packaging.

About Orbotech Ltd.
Orbotech Ltd. (NASDAQ/GSM:ORBK) has been at the cutting edge of the electronics industry supply chain, as an innovator of enabling technologies used in the manufacture of the world’s most sophisticated consumer and industrial products, for over 30 years. The Company is a leading provider of yield-enhancing and production solutions, primarily for manufacturers of printed circuit boards, flat panel displays and other electronic components. Today, virtually every electronic device is produced using Orbotech technology. The Company also applies its core expertise and resources in other advanced technology areas, including character recognition for check and forms processing and solar photovoltaic manufacturing. Headquartered in Israel and operating from multiple locations internationally, Orbotech’s highly talented and inter-disciplinary professionals design, manufacture, sell and service the Company’s end-to-end portfolio of solutions for the benefit of customers the world over. For more information please see the Company’s filings with the SEC at www.sec.gov and visit the Company’s corporate website at www.orbotech.com. The corporate website is not incorporated herein by reference and is included as an inactive textual reference only.

Company Contact:

Ann Michael

Senior Corporate Marketing Communications Manager

Orbotech Ltd.

Tel: +972.8.942.3148

ann(michael)@orbotech.com
Contact Information
Ann Michael, Senior Corporate Marcom Manager
Orbotech Ltd.
+972 89423148

Online Web 2.0 Version
You can read the online version of this press release here.